

Table of Contents

Introduction
Introduction to Field Upgrade Using IAP
Design Example Overview
Design Description
IAP Programming: eNVM Update in Release Mode Using the IAP Through UART
Running the Design
Conclusion
Appendix A
Appendix B
List of Changes

Introduction

The SmartFusion[®] customizable system-on-chip (cSoC) FPGAs devices integrate FPGA technology with hardened ARM[®] Cortex[™]-M3 processor based microcontroller subsystem (MSS) and programmable high-performance analog blocks built on a low power flash semiconductor process. The MSS consists of hardened blocks, such as a 100 MHz ARM Cortex-M3 processor, peripheral DMA (PDMA), embedded nonvolatile memory (eNVM), embedded SRAM (eSRAM), embedded FlashROM (eFROM), external memory controller (EMC), Watchdog Timer, Phillips Inter-Integrated circuit (I²C), SPI, 10/100 Ethernet controller, real-time counter (RTC), general purpose input output (GPIO) block, fabric interface controller (FIC), in-application programming (IAP), and system registers. The programmable analog block contains the analog compute engine (ACE) and analog front-end (AFE) consisting of ADCs, DACs, active bipolar prescalers (ABPS), comparators, current monitors, and temperature monitor circuitry.

The IAP block is the portion of the MSS that interfaces with the Cortex-M3 processor through the APB bus. The IAP block provides the hardware capability to program the flash components of the SmartFusion cSoC device within the programmed end users application. The flash components are: an FPGA array, the MSS eNVM, and the FlashROM.

Re-programming the eNVM blocks (field upgrading the firmware/software) using the Cortex-M3 processor is achieved by executing the eNVM programming algorithm from eSRAM. Since individual pages (132 bytes) of the eNVM can be write-protected, the programming algorithm software can be protected from inadvertent erasure. When reprogramming the eNVM, both MSS I/Os and FPGA I/Os are available as interfaces for sourcing the new eNVM image.

The executable image for Cortex-M3 processor can be partitioned across the following memories of the SmartFusion cSoC device:

- 1. Internal Memories: eNVM, eSRAM, and fabric RAM
- 2. External memories: Connected through EMC interface (SRAM, PSRAM, SSRAM, and NOR flash)

Based on the application's requirement and various combinations of the above memories, the executable application can be created. Linker script is used by the linker to create the required image. This application introduces the usage of the linker script generator tool for the SmartFusion cSoC Cortex-M3 processor executable.



This application note demonstrates the following using the SmartFusion cSoC:

- A basic bootloader for the SmartFusion cSoC device has multiple images in the eNVM with different memory maps. It boots the required image as per the need. The bootloader should be designed and implemented as a black box. For this you need to parse the complete *.elf files that are loaded or to be loaded in eNVM/EMC flash, which requires more memory and booting time. The bootloader proposed in this application note is not a full-fledged bootloader, but is used as a reference example to boot multiple images.
- 2. Making a complete release mode image to run from eSRAM. This image is stored in the eNVM and the bootloader relocates this image if it is selected for execution. This is an example of using the eSRAM as a complete executable memory and booting using the bootloader.
- 3. Performing the IAP programming to update the partial or complete eNVM in release mode. This requirement is accomplished using the above two steps.

Introduction to Field Upgrade Using IAP

The IAP interface in the SmartFusion cSoC device is used by the Cortex-M3 processor to perform the upgrade or programming of eNVM and/or FPGA fabric. Figure 1 shows a typical SmartFusion cSoC device configuration customized for performing the IAP.



Figure 1 • Block Diagram for the IAP Programming for eNVM and/or FPGA Fabric

The IAP interface is a part of the digital subsystem which is an APB peripheral to the Cortex-M3 processor. This peripheral block is a combination of both hardware and firmware that provides low level interface to program the flash component of the SmartFusion cSoC device through the control and status registry.



This block performs the following:

- Mimic the JTAG signals through the existing test access ports
- Manage the data stream communication from the source to the IAP block



Figure 2 • IAP Data Flow Block Diagram



In release mode, while updating the eNVM content, the programming code (IAP Programmer) should not reside on the eNVM as it cannot be reprogrammed and accessed simultaneously.

For this reason we need to design a multi-boot system with the eNVM partitioned into multiple regions as follows:

- Bootloader/eNVM Region 1: It provides the option to select the IAP Programmer (eNVM Region 2) or application code (eNVM Region 3) and boot the selected executable image.
- IAP Programmer/eNVM Region 2: It contains the IAP executable image that is built to run completely from the eSRAM in release mode. The bootloader copies this partition to eSRAM if you have selected IAP programming.
- Application/eNVM Region 3: The IAP Programmer running from eSRAM programs this region using the *.dat file provided by you. This program is launched by either the IAP Programmer after programming the *.dat file into this region successfully, or by the bootloader if this has been programmed earlier based on your selection. Figure 3 illustrates the partitioning of the eNVM for mutually exclusive executable images.





The memory regions shown in Figure 3 are used in this application note as a example memory map. There is no specific rule for the memory maps for the applications. The memory maps explained in this application note are just for reference. As per the applications memory, these requirements can be changed and the corresponding linker scripts can be generated.

The simple approach for understanding these memory requirements for these applications, you can use the partitions explained in this application note as it is and generate the linker scripts. While compiling the projects, the compiler notifies you if the memory regions are not sufficient, if so, adjust the partitions accordingly. There are still possibilities that the compiler generates code that may have runtime errors like heap and stack collisions etc. In such cases the data regions and stack sizes have to be adjusted as per the applications run time memory requirements.

Design Example Overview

The design example consists of the following mutually exclusive executable images that reside on eNVM.

- 1. Bootloader
- 2. IAP Programmer
- 3. Example application



Both eNVM and eSRAM are partitioned into multiple regions to run this multi-boot system design. Each design uses different linker scripts with different memory maps. A linker script generator tool is used to generate different linker script files with different memory maps as listed below:

- 1. Bootloader
 - 64 KB of eNVM for interrupt vector table, instructions, and constant data sections
 - 4 KB of eSRAM for stack, heap, and data sections
- 2. IAP Programmer completely running from eSRAM
 - 60 KB of eSRAM for all the sections of an executable image
- 3. Simple application image
 - 128 KB of eNVM for interrupt vector table, instructions, and constant data sections
 - 64 KB of eSRAM for stack, heap, and data sections

The reason for creating the second image that will run exclusively from the eSRAM is to run an executable image independent of eNVM in a release mode or end product. This is required to use an IAP interface to update partial or full eNVM in release mode. You cannot update the eNVM while the IAP Programmer is running from eNVM.

Design Description

Bootloader

The bootloader performs the function of relocating or loading (copying the different sections of image to their executable location from loaded location) and making other executable images to run or debug. The bootloader needs the inputs related to the starting address of the executable image residing in the system memory map.

As explained in the Figure 3 on page 4, we will be having two images in eNVM apart from the bootloader from which you can provide the input about the application that has to be executed by the bootloader. The Bootloader is also provided with the timeout feature in which if you do not select any input for booting within the timeout period, the bootloader boots the default sample application image from Region 3. In the design files provided for this application note, the boot time parameter is provided in the boot_config.h file. Timeout can vary by changing this parameter as per the applications requirements.

When the image is selected, the bootloader initializes the Cortex-M3 processor stack pointer and PC to the new image's reset handler. Once the image or sections of the image have been loaded to appropriate memories, the bootloader performs the steps explained in Figure 4 on page 6 to branch to the newly loaded image execution.

In this basic bootloader implementation, the executable image runs from the eSRAM and the bootloader copies the entire image of 60 KB size from eNVM Region 2 to the bottom of the eSRAM.

The executable images residing in eNVM Region 1 (bootloader) and eNVM Region 3 (sample application) are created to be executed in place from the eNVM and hence no copying is required.

The reset handler of each image takes care of the executable image section replacements in all cases. If all the images are created to be executed in place of eNVM, then there is no requirement for copying the image from one location to other. In this particular example, we need to create an IAP Programmer image to be executed completely from eSRAM and hence in the bootloader implementation, copying logic to copy from eNVM Region 2 to eSRAM is implemented.



```
*_____
* Branch to an application startup code: Theory of operation:
* Step 1:
*
      Load the address of the vector table into RO.
* Step 2:
      Load the application's initial stack pointer value into R1.
*
* Step 3:
*
      Load the address of the Cortex M3 vector table Offset register into R2.
*
  Step 4:
      Load the application's initial stack pointer to CortexM3 vector table
      Offset registerSCB VTOR.
  Step 5:
^{\star}
      Load the applications's reset handler address into the Link Register.
      The location at address RO + 0x04 is the reset vector,
*
      RO being the base address of the vector table.
*
  Step 6:
      Load the application's initial stack pointer to
^{\star}
      the Main Stack Pointer register.
* Step 7:
*
      Return from the function by branching to the Link Register. This causes
*
    to branch to the application's startup code/Reset Handler.
*/
   .align 4
www.user_code_esram:
   ldr r0,=VECTOR TABLE ADDR /* Step 1. */
                            /* Step 2. */
/* Step 3. */
   ldr r1,[r0,#0x0]
   ldr r2,=SCB VTOR ADDRESS
   str rO, [r2]
                             /* Step 4. */
   ldr lr,[r0,#0x4]
                             /* Step 5. */
                             /* Step 6. */
   msr msp,r1
                             /* Step 7. */
   bx lr
   .end
```

Figure 4 • Steps of the Bootloader to Jump to the New Image



IAP Programming: eNVM Update in Release Mode Using the IAP Through UART



Following is the flow chart of the example bootloader Implemented for this application note:

Figure 5 • Flow Chart of the Basic Bootloader Implemented

IAP Programming: eNVM Update in Release Mode Using the IAP Through UART

In release mode, while programming eNVM using the IAP interface, the sections of the programming code (IAP Programmer) should not reside on eNVM. This is because accessing eNVM simultaneously using the Cortex-M3 processor and IAP (JTAG) signals is not possible. Hence, we need to run the complete programming code from eSRAM or external memories in such a way that no part of the code or data of IAP programming is accessed by the Cortex-M3 processor from eNVM.

This application note explains the complete procedure on how this requirement can be met by designing and implementing using the multiple executable images. These executable images include the bootloader and IAP Programmer. The linker scripts for these executable images are generated by using

the linker script generator tool for various memory map regions.

This application uses the host loader to get the programming file or *.dat file content from the host PC using the UART as the host interface between Host PC and the SmartFusion cSoC device. Figure 6 on page 8 displays the flow chart of the complete IAP programming for the eNVM by getting the *.dat file or programming file from the host PC.





Figure 6 • Flow Chart of IAP Programming Through UART

There are various possible methods for getting the *.dat file to the IAP Programmer, such as internet or Ethernet, on board memories (SPI Flash) etc. All these methods of IAP programming are explained in the *SmartFusion cSoC: Programming FPGA Fabric and eNVM Using In-Application Programming Interface* application note.



IAP Programming: eNVM Update in Release Mode Using the IAP Through UART

Using the Linker Script Generator Tool

The comprehensive user guide of the linker script generator is covered in "Appendix B" on page 19 of this document. For creating the linker scripts for this design example, use the following settings in the linker script generator as provided below:

- 1. The executable image of the basic bootloader uses the following memory space:
 - 64 KB of eNVM for interrupt vector table, instructions, and constant data sections
 - 4 KB of eSRAM for stack, heap, and data sections

Figure 7 shows the LDF Generator with options selected for the bootloader example.

C Debug		_		File Name 🛛 🗤 🕅	-bootloader-exa	mple 6
Production		1	\square	,		
Memory Type			Sectio	ns		
Memory Type Starting Address	Size		Init	rom1		-
RAM1 0x 2000F000	4k	2)	Text	rom1		• 7
RAM2 0x 70000000	4M		Data	a ram1		•
RAM3 0x 0	0		– User S	ection		
ROM1 0x 60000000	64k	3		Section Name		1
F ROM2 0x 74000000	16M			Section Name	Tusei_section	-
E ROM3 0x 0	0			Section Type	text	O data
				Location	ram1	~
itack		_				
Location ram1	Size 2k	4	Г	Section Name	user_section	2
ave Location				Section Type	text	🔿 data
Location D:/Projects/GUI/Linker Se	cript/LD_Jur_Browse	5		Location	ram1	Ŧ

Figure 7 • LDF Generator with Options Selected for the Bootloader Example

The above selection generates the linker script with the memory map shown in Figure 8 on page 10 for the bootloader image.





Figure 8 • Memory Regions Used for the Bootloader Example

 The IAP Programmer completely running from eSRAM uses 60 KB of eSRAM for all the sections of an executable image. Figure 9 shows the LDF Generator with settings for a production mode image that completely runs from eSRAM.

C Debug Production	1	ה(File Name execute-in-place-esram 6
Memory Type	Circ	1	Sections
RAM1 0x 20008000	28k 2		Text rom1 7
□ RAM2 0x 70000000	4M 0	ļ	Data ram1
R0M1 0x 20000000 R0M2 0x 20000000	32k 3	3	Section Name user_section1
□ ROM2 0x 0	0		Section Type 🌀 text 🔿 data
Stack			Location ram1
Location ram1	Size 8k 4	ŧĴ	Section Name user_section2
Save Location			Section Type I text C data
Location D:/Projects/GUI/Linker Sc	ript/LD_Jur Browse	5	

Figure 9 • LDF Generator With Options Selected for Production Mode Image Only Running From eSRAM



IAP Programming: eNVM Update in Release Mode Using the IAP Through UART

3. The settings in the Figure 9 on page 10 generate the linker script with the memory map shown in Figure 10 for a production mode image. In this application note, this linker script is used to build the IAP Programmer algorithm implemented in software with eSRAM memory map.





- 4. For a simple sample application image the following memory space is used:
 - 128 KB of eNVM for interrupt vector table, instructions, and constant data sections
 - 64 KB of eSRAM for stack, heap, and data sections



Figure 11 shows the LDF Generator with options selected for the sample application.

74 LDF Generator V1.0		
Linker Description Type		Linker Description File Name
C Debug		Ed. File Name Johnson anum 2rdPagind
Production	1	
Memory Type		Sections
Memory Type Starting Address	Size	Init rom1 🔹
RAM1 0x 20000000	64k 2	Text rom1 • 7
RAM2 0x 7000000	4M	Data ram1 🔹
🗖 RAM3 0x 🛛	0	User Section
ROM1 0x 60020000	128k 3	Section Name User section1
ROM2 0x 74000000	16M	
F ROM3 0x 0	0	Section Type (• text) data
Charle		Location ram1
Siduk		
Location ram1	Size 8k 4	Section Name user_section2
- Save Location		Section Type 💿 text 💿 data
Location D:/Projects/GUI/Linker S	cript/LD_Jur Browse 5	Location ram1 -
Generate 8	Exit	Help

Figure 11 • LDF Generator with Options Selected for Sample Application

The above selection generates the linker script with the memory map shown in Figure 12 on page 13 for the sample application. This sample application is implemented to display the text on both HyperTerminal and OLED.







Board Settings

The design example works on the SmartFusion Development Kit Board with default board settings. Refer to the following user's guide for default board settings:

• SmartFusion Development Kit User's Guide

Running the Design

Refer to "Appendix A" on page 19 for complete details and links to the design files. Figure 13 shows the directory structure of the design.

4 👪 A2F_AC372_DF
4 퉬 A2F500
🛛 🏭 component
퉬 constraint
퉬 coreconsole
> 퉱 designer
Þ 鷆 firmware
🍑 hdl
鷆 phy_synthesis
鷆 simulation
鷆 smartgen
4 🎍 SoftConsole
A 👘 WSSTAD-WSS_CM3_0
> 🕌 .metadata
D 🎍 IAP_UART
Image1BootLoader
Image3Application
MSS_IAP_MSS_CM3_0_hw_platform
🕌 stimulus
V is synthesis
🌉 tooldata
> 🛄 viewdraw
UF_Generator
🖻 🏢 Programming File

Figure 13 • Directory Structure of the Design Example



- 1. The A2F500 folder contains the HW project for the A2F500 SmartFusion SoC.
- 2. The SoftConsole folder contains the following:
 - IAP_UART: Contains the software for the IAP programming using the UART. The UART is the communication channel for transferring the *.dat file (input file from HOST to A2F).
 - Image1BootLoader: This folder contains the software for the basic bootloader to prompt you
 about the available images in eNVM and boot the selected image by using your input.
 - Image3 Application: This folder contains the reference application image to be loaded at the third region of the eNVM by IAP.

Step 1: Procedure to create the eSRAM image in release mode.

This step is required if the IAP_UART project is going to be re-built for any reason, such as updates. If the project IAP_UART is not going for an update or re-compilation then skip this step.

- 1. Launch the SoftConsole project, double-click **Write Application Code** under **Develop Firmware** in the Libero[®] System-on-Chip (SoC) design flow window.
- 2. Clean and build the application using the ld file "production-execute-in-place-esram.ld". This is already configured as the default ld file for this project.
- 3. Once the image is build, open the folder: \A2F_AC372_DF\A2F500\SoftConsole\MSS_IAP_MSS_CM3_0\IAP_UART\UART_HostPC\IAP_UART_From_HostPC_ws\latest_IAP_Prj\Debug and open the *.hex (here IAP_SC.hex). It is displayed as shown in Figure 14. Remove the first line (line 1) of this image by opening it in any text editor in such a way that the second line becomes the first line and then save the file.





4. The above step is required to make this image suitable for the eNVM client. Because of the header generated in the eSRAM image, this image is not interpreted correctly as the eNVM client and it is not accepted as image or data file for the eNVM client in Libero SoC tool flow also. Hence, we need to remove the above header information from the Figure 14 to make this the data file for the eNVM client.

The edited *.hex file is displayed as shown in the Figure 15.



Figure 15 • Edited Hex Image of the IAP Programmer



Step 2: Program the provided STP file on the SmartFusion Development Kit Board.

You may need to re-import the *.hex file into eNVM data client in the MSS and save it if there are any changes in the path of the *.hex files or any updates are made to the *.hex files and generate the new STAPL file.

\A2F_AC372_DF\A2F500\designer\impl1\IAP_TOP_fp\IAP_TOP.stp

Step 3: Connect the mini USB cable (USB-RS232) between the USB connector on the SmartFusion Development Kit Board and a USB port of your computer.

Start a HyperTerminal session with a 57600 baud rate, 8 data bits, 1 stop bit, no parity, and no flow control. If your computer does not have the HyperTerminal program, use any free serial terminal emulation program, such as PuTTY or Tera Term. Refer to the *Configuring Serial Terminal Emulation Programs* tutorial for configuring HyperTerminal, Tera Term, or PuTTY.

Step 4: Power cycle the board and follow the help provided in the PuTTy.

Figure 16 shows the Menu of the demo design on the PuTTy.



Figure 16 • Menu of the Demo Design on the PuTTy

If input is not provided by the user within 30 seconds then the application from Region 3 will be executed automatically. Figure 17 shows the automatic booting of application image after timeout.

B COM3 - PuTTY	
ŧ### SmartFusion Bootloader Example ####	^
Please Select the Following option with in 30 Secs	
1. IAP Programmer (Region 2)	
 Application (Region 3)-> Default bootImage 	
Timeout occurred Booting application (3rd Image)	
ŧ### SmartFusion Boot loader Example ####	
Image3 is Running form eNVM region 3	
Image3 is Running form eNVM region 3	
Image3 is Running form eNVM region 3	
Image3 is Running form eNVM region 3	
Image3 is Running form eNVM region 3	
	E
	-

Figure 17 • Booting the Application if User Input is Not Provided



Step 5: If option 1 is selected, the IAP Programmer will be launched by the bootloader.

The IAP Programmer loads or programs the application image into Region 3 or eNVM locations with which the *.dat file is created. So, before selecting this option, create the *.dat file if you wish to change the eNVM programming *.dat file.If you want to create a new *.dat file for FPGA fabric and eNVM, follow the steps given below:

- 1. Create a Libero SoC project
- 2. Create eNVM data client in MSS
- 3. Create desired logic in FPGA, connect to the MSS if required
- 4. Go through the Synthesis, and designer flow
- 5. Open the FlashPro and export the programming file as a DirectC file (*.dat), using **File > Export > Export Single Programming File**.

The *.dat file used for this application demo is located at:

\A2F_AC372_DF\A2F500\SoftConsole\MSS_IAP_MSS_CM3_0\IAP_UART\UART_HostPC\IAP_UART_ From_HostPC_ws\host_tool (file three_eNVM_Images_withOLED.dat at this location is the prebuilt image for this design).

To create or update the application image with the same memory map of this application note, use the *.ld file provided in the application project located at:

 $\label{eq:label_app_pri} \end{tabular} $$ A2F_AC372_DFA2F500\SoftConsole\MSS_IAP_MSS_CM3_0\Image3Application\simple_app_pri\production-execute-in-place-envm-3rdRegion.ld $$ are also as a second structure of the second st$

Once the dat file is created or updated for eNVM regions, follow the instructions on PuTTy (Figure 18).



Figure 18 • Menu After the IAP Programmer Selection

Step 6: Open the host loader

As explained in step 5, disconnect the serial terminal and open the host loader located at \A2F_AC372_DF\A2F500\SoftConsole\MSS_IAP_MSS_CM3_0\IAP_UART\UART_HostPC\IAP_UART_ From_HostPC_ws\host_tool\IAP_Direct_Uart.exe with the parameters as shown in the Figure 19. The first parameter is the programming input file and the last parameter to the *.exe file is the COM port



number. The COM port number may vary for each system. Check the COM port number to which the USB2UART port is connected. Press **ENTER** to execute this command.

🚾 C:\Windows\system32\cmd.exe	
Microsoft Windows [Version 6.1.7601] Copyright (c) 2009 Microsoft Corporation. All rights reserved.	·
C:\Users\uppalapatir>cd\	
C:\>cd C:\A2F_AC372_DF\A2F500\SoftConsole\MSS_IAP_MSS_CM3_0\IAP_UART\ \IAP_UARI_From_HostPC_vs\host_tool	UART_HostPC
C:\A2F_AC372_DF\A2F500\SoftConsole\MS_IPF_MS_CH3_0\IPF_UART\UART MT_From_HostFC_us\nost_son1}IAP_Direct_Uart_exe_C:\A2F_AC372_DF\A2F50 Ie\MSS_IAP_MSS_CM3_0\IAP_UART\UART_HostPC\IAP_UARI_From_HostFC_vs\hos e_eNVM_Images_withOLED.dat 3_	stPC\IAP_UA Ø\SoftConso t_tool\thre

Figure 19 • Host Tool Usage For Sending the .dat File From Host to SmartFusion

Step 7: There will be continuous debug statements on the command window of the host IAP Programmer.

Here, the output of the provided design automatically boots the device and user can change the design as per the application requirements. At the end of the IAP programming you can view the information appearing on the command prompt as shown in Figure 20.



Figure 20 • Menu of the Host Tool After Completion of the Programming



The above step performs the IAP programming and boots the third eNVM region image. To check this, connect PuTTy once again. The output information is displayed as shown in Figure 21.



Figure 21 • Message of the eNVM Image 3 Application on PuTTY

Note: When you regenerate the MSS component from Libero SoC project, ensure that the following lines are commented out in softconsole project workspace.

MSS_IAP_MSS_CM3_0_hw_platform library module:

File name : DirectC/dpcom.c

```
Line number 125: // #error "Please add code here to get the programming data. Please refer to the Required Source Code Modifications section of the DirectC user's guide." File name : DirectC/dpuser.c
```

Line number 15 : //#include "main.h" Line number 48 ://#error "Please modify this function to time delays. Please refer to the Required Source Code Modifications section of the DirectC user's guide."

Release Mode

The release mode programming file (STAPL) is also provided. Refer to the Readme.txt file included in the programming file for more information. Refer to *SmartFusion cSoC: Building Executable Image in Release Mode and Loading into eNVM* tutorial for more information on building an application in release mode.

Conclusion

This application note explains the design and implementation of the following solutions for the SmartFusion cSoC:

- 1. A basic bootloader to create multiple executable images in a system and boot the input requested image.
- 2. Creating a release mode image to run completely from eSRAM.
- eNVM programming in release mode programming the partial or full eNVM from IAP Programmer running from the eSRAM.



Appendix A

Design files

You can download the design files from the Microsemi SoC Products Group website:

www.microsemi.com/soc/download/rsc/?f=A2F_AC372_DF.

The design file consists of Libero SoC projects and SoftConsole software projects. Refer to the ReadMe.txt file for directory structure, description, and software versions.

You can download the programming files (*.stp) in release mode from the Microsemi SoC Products Group website: www.microsemi.com/soc/download/rsc/?f=A2F_AC372_PF.

The programming file consists of STAPL programming file (*.stp) for A2F500-DEV-KIT and a Readme.txt file.

Appendix B

Linker Description File (LDF) Generator Utility

This section explains the use of LDF Generator utility for creating LDFs also called Linker Scripts for SmartFusion cSoC systems. This version of LDF Generator supports only SoftConsole. This document assumes that you already have a basic understanding of the role of Linker and LDF. Refer to *Using Id, the GNU linker* document for more details on Linker and LDF.

A basic understanding of the SmartFusion design flow is assumed. Refer to Using UART with SmartFusion cSoC - Libero SoC and SoftConsole Flow Tutorial to understand the SmartFusion design flow.

LDF Generator Overview

The LDF Generator utility is a powerful graphical user interface (GUI) tool that provides you an easy and convenient way to create LDFs. It reduces the complexity of writing linker scripts that involves complex tasks such as memory map, code, data placement, stack or heap usage etc.



Figure 22 shows a screenshot of the LDF Generator utility.

Linker Description Type © Debug © Production-Execute-In-Place	1 File Name Linker_Description_File 5
Memory Type Starting Address Size Image: RAM1 Ox 2000000 64k Image: RAM2 Ox 70000000 4M Image: RAM3 Ox 70 0 Image: RAM3 Ox 70 0 Image: RAM3 Ox 70 0 Image: ROM1 Ox 60000000 256k Image: ROM2 Ox 74000000 16M Image: ROM3 Ox 70 0 Stack 5	2 Init ram1 • 6 Text ram1 • 6 Data ram1 • User Section User Section Name User_section1 7 Section Type • text • data Location ram1 •
Location ram1 Size 8k Save Location Location D:/Projects/APPNOTE/Linker_Descri	3 Section Name user_section2 Section Type I text I data Location ram1

Figure 22 • Linker Description File Generator

The LDF Generator mainly consists of seven segments. You need to enter or select the following parameters:

- 1. Linker Description Type
- 2. Memory Type
- 3. Stack
- 4. Save Location
- 5. Linker Description File Name
- 6. Sections
- 7. User Sections



Linker Description Type

The LDF type can be selected as either **Debug** or **Production**. There are two radio buttons under the **Linker Description Type** as shown in Figure 23 for selection the LDF type. The default value is **Debug**.



Figure 23 • Linker Description File Type Selection

In the **Debug** mode, initialized global and static variables, and uninitialized global and static variables are stored in Read-Write memories (eSRAM and EMC SRAM). The **Debug** mode supports debugging from eSRAM/EMC SRAM and eNVM. If 'ROM1' is selected as memory location for sections or user section, the LDF Generator creates LDF for debugging from eNVM. If 'ROM1' is not selected for sections or user sections, the LDF Generator creates LDF for debugging from eSRAM/EMC SRAM.

In the **Production** mode, initialized global and static variables, and uninitialized global and static variables are stored in Read only Memories (eNVM) and copied back into Read-Write memories at startup.

Memory Type

The **Memory Type** section provides options to select two Read-Write memories and one Read-Only memory. Based on the **Sections** (Init, Text, and Data) storage type (Read-Write/Read-only), the **Memory Type** needs to be selected and the **Starting Address** and **Size** need to be provided.

The **Starting Address** should be in 8-digit Hexadecimal format and the **Size** can be in Kilobytes/Megabytes (for example 64k or 2M). Figure 24 on page 21 illustrates an example Memory Type selection.

Memo	лу Туре -]
Mem	ory Type	Starting Address	Size
	RAM1	0x 20000000	64k eSRAM
	RAM2	0x 7000000	4M EMC SRAM
	RAM3	0x 0	0
	ROM1	0x 60000000	256k eNVM
	ROM2	0x 74000000	16M
Г	R0M3	0x 0	0

Figure 24 • Memory Type Selection



Stack

The **stack** frame provides you the option to select the stack Location and Size. The default stack location is 'ram1'. The stack location and data section location should be same (that is both stack location and data section in 'ram1' or in 'ram2'). The default stack size is 8k. You can change the stack size based on the design requirements. Figure 25 illustrates an example stack memory location selection.



Figure 25 • Stack Location and Size

Save Location

The LDF Generator provides you the option to browse to the directory where the generated LDF needs to be saved. The default location is the current working directory. Figure 26 shows the save location for the generated LDF.

- Save Locati	on)
Location	D:/Projects/APPNOTE/Linker_Descri	Browse



Linker Description File Name

The default name is either Debug or Production based on Linker Description File Type selection. You can type the desired **File Name** in the text field under **Linker Description File Name** as shown in Figure 27.

Г	Link	er Descriptior	n File Name	
		File Name	SmartFusion_LD	
L				

Figure 27 • Changing the Linker Description File Name



Sections

The LDF Generator provides the options to select the following sections and its memory types:

- 1. Init (Cortex-M3 processor vector table)
- 2. Text
- 3. Data

Init, Text, and Data are default sections in the LDF and its memory type needs to be selected from the drop-down menu based on design requirements.

Init

The vector table can be stored in the Read-Write memory or Read-only memory. The LDF Generator provides you the option to select two Read-Write memories and one Read-only memory from the drop-down menu. Figure 28 shows the Init section memory selection.



Figure 28 • Init Section Memory Selection

Text

The **Text** section represents the instruction in the program that can be stored in the Read-Write memory or Read-Only memory. The LDF Generator provides you the option to select two Read-Write memories and one Read-only memory from the drop-down menu. Figure 29 shows the Text section memory selection.



Figure 29 • Text Section Memory Selection



Data

The **Data** section consists of initialized global and static variables that can be stored in the Read-Write memory only. The LDF Generator provides you the option to select two Read-Write memories from the drop-down menu. Figure 30 shows the Data section memory selection.



Figure 30 • Data Section Memory Selection

User Section

The LDF Generator provides you the option to select two user defined sections. The section type of each user defined section can be either Text section or Data section. Figure 31 shows the **User Section** selection. You can select either or both check buttons to enable user sections.

Section Name	user_section1	
Section Type	• text	🔿 data
Location	ram1 ram1 ram2	•
Section Name	rom1	
Section Type		
Location		
	Section Type Location Section Name Section Type Location	Section Type text Location Fam1 ram2 rom1 Section Type Location

Figure 31 • User Section Selection



Once you select any one of the user sections, you need to append the source file with the following attribute to the above functions and/or data declarations that need to be in the user sections.

Once you select any one of the user sections, the LDF Generator pops up a warning message as shown in Figure 32 before generating the linker scripts.

74 Warning 🛛 🔀
You have selected the User Section ! Please append the source file with following attribute to above the functions and/or data declarations that needs to be in user sections.
attribute((section ("name_of_user_section")));
e.g.
void hyperterminal_task(void *para)attribute((section(".usersection1"))); void hyperterminal_task(void *para) {
}

Figure 32 • Attribute Example for User Sections



List of Changes

The following table lists critical changes that were made in each revision of the document.

Revision*	Changes	Page
Revision 4 (January 2013)	Added "Board Settings" section under "IAP Programming: eNVM Update in Release Mode Using the IAP Through UART" section (SAR 43469).	13
Revision 3 (April 2012)	Replaced Figure 13 (SAR 38335)	13
	Modified Step 1 under "Running the Design" section (SAR 38335)	13
	Modified Step 5 under "Running the Design" section (SAR 38335)	13
	Replaced Figure 19 (SAR 38335)	17
	Replaced Figure 20 (SAR 38335)	17
Revision 2 (February 2012)	Removed ".zip" extension in the Design files link (SAR 36763).	19
	Modified Step 7 listed under "Running the Design" section (SAR 36683).	13
Revision 1 (January 2012)	Modified text in Step 1, Step 2, Step 5 and Step 6 listed under "Running the Design" section (SAR 35871).	13 to 17
	Added a section called "Release Mode " (SAR 35871).	18
	Modified "Appendix A" section (SAR 35871).	19

Note: *The revision number is located in the part number after the hyphen. The part number is displayed at the bottom of the last page of the document. The digits following the slash indicate the month and year of publication.



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